



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Innovative **Technology**
for a **Connected** World

Tflex™ SF600 Series Thermal Gap Filler



COMPLIANT SILICONE-FREE 3.0 W/mK THERMALLY CONDUCTIVE GAP FILLER

Tflex™ SF600 is a high performance, silicone-free thermal gap filler with a conductivity of 3.0 W/mK. Tflex™ SF600 is designed for applications which are silicone sensitive. This material is RoHS compliant.

FEATURES AND BENEFITS

- Silicone-free gap pad
- Thermal Conductivity for material thicknesses of 10 to 30 mils is 2.8 W/mK
- Thermal Conductivity for material thicknesses of 40 to 140 mils is 3.0 W/mK
- Available in thicknesses from 0.010-inch (0.25 mm) through 0.140-inch (3.56 mm) in 0.010-inch increments

APPLICATIONS

- Automotive applications
- Applications involving optical components
- Flat panel displays
- Hard drives

global solutions: local support.™

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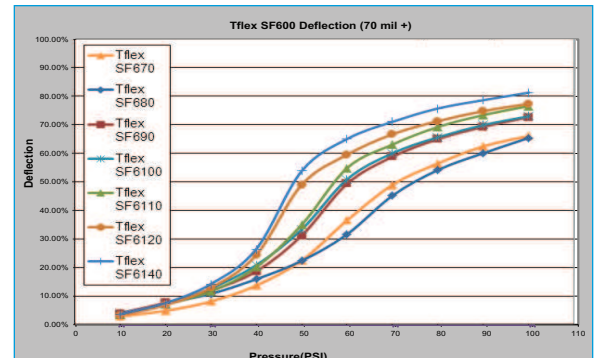
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www.lairdtech.com/thermal

Tflex™ SF600 TYPICAL PROPERTIES

	Tflex™ SF600	TEST METHOD
Construction	Boron Nitride filled gap pad	NA
Color	Rose	visual
Thermal Conductivity	3.0 W/mK	Hot Disk
Hardness (Shore 00)	80 Shore 00; 3 seconds	ASTM D2240
Density	1.27 g/cc	Helium Pycnometer
Standard Thickness Range	0.010 - 0.140 inches (0.25 - 3.56 mm)	
Volume Resistivity	10 ¹⁴ ohm-cm	ASTM D257
UL Flammability Rating	V0 (pending)	UL 94
Continuous use temperature	-20° to 125°C	TGA
Weight Loss at 125°C	<0.1% over 24 hrs	TGA
Dielectric Constant @ 1 kHz	3.5	ASTM D150



STANDARD THICKNESSES

Standard thickness is 0.010-inch (0.25 mm) through 0.140-inch (3.56 mm) and available in 0.010-inch (0.25 mm) increments. 0.010-inch is only available in custom cut parts (sheet material is not available).

MATERIAL NAME AND THICKNESS

Tflex™ indicates Laird Technologies' brand thermally conductive elastomeric gap filler product. SF6xx indicates 'SF600 series' 3.0 W/mK material, and xxx indicates thickness in mils (0.001-inches)

Examples:

Tflex™ SF620 = 0.020-inch thick material

THR-DS-Tflex-SF600 0412

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